

# CD74HC4017

Data sheet acquired from Harris Semiconductor SCHS200

November 1997

# High Speed CMOS Logic Decade Counter/Divider with 10 Decoded Outputs

#### **Features**

- Fully Static Operation
- Buffered Inputs
- Common Reset
- · Positive Edge Clocking
- Typical  $f_{MAX} = 50MHz$  at  $V_{CC} = 5V$ ,  $C_L = 15pF$ ,  $T_A = 25^{o}C$
- Fanout (Over Temperature Range)
  - Standard Outputs................................. 10 LSTTL Loads
  - Bus Driver Outputs ........... 15 LSTTL Loads
- Wide Operating Temperature Range ... -55°C to 125°C
- Balanced Propagation Delay and Transition Times
- Significant Power Reduction Compared to LSTTL Logic ICs
- HC Types
  - 2V to 6V Operation
  - High Noise Immunity:  $N_{IL}$  = 30%,  $N_{IH}$  = 30% of  $V_{CC}$  at  $V_{CC}$  = 5V

## Description

The Harris CD74HC4017 is a high speed silicon gate CMOS 5-stage Johnson counter with 10 decoded outputs. Each of the decoded outputs is normally low and sequentially goes high on the low to high transition clock period of the 10 clock period cycle. The CARRY (TC) output transitions low to high after OUTPUT 10 goes low, and can be used in conjunction with the CLOCK ENABLE  $(\overline{CE})$  to cascade several stages. The CLOCK ENABLE input disables counting when in the high state. A RESET (MR) input is also provided which when taken high sets all the decoded outputs, except "0", low.

The device can drive up to 10 low power Schottky equivalent loads.

#### **Ordering Information**

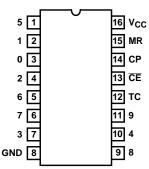
PART NUMBER TEMP. RANGE (°C)		PACKAGE	PKG. NO.
CD74HC4017E	-55 to 125	16 Ld PDIP	E16.3

#### NOTES:

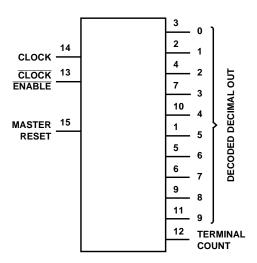
- 1. When ordering, use the entire part number. Add the suffix 96 to obtain the variant in the tape and reel.
- Wafer or die for this part number is available which meets all electrical specifications. Please contact your local sales office or Harris customer service for ordering information.

#### **Pinout**

CD74HC4017 (PDIP) TOP VIEW



# Functional Diagram



#### TRUTH TABLE

СР	CE	MR	OUTPUT STATE †
L	X	L	No Change
Х	Н	L	No Change
Х	Х	Н	"0" = H, "1"-"9" = L
1	L	L	Increments Counter
<b>\</b>	Х	L	No Change
Х	1	L	No Change
Н	<b>↓</b>	L	Increments Counter

### NOTE:

H = High Level L = Low Level

 $\uparrow$  = High to Low Transition

 $\downarrow$  = Low to High Transition

X = Don't Care.

 $\dagger$  If n < 5 TC = H, Otherwise = L

#### CD74HC4017

### **Absolute Maximum Ratings**

DC Supply Voltage, V <sub>CC</sub> 0.5V to 7V
DC Input Diode Current, I <sub>IK</sub>
For $V_I < -0.5V$ or $V_I > V_{CC} + 0.5V$
DC Output Diode Current, I <sub>OK</sub>
For $V_O < -0.5V$ or $V_O > V_{CC} + 0.5V$ ±20mA
DC Output Source or Sink Current per Output Pin, IO
For $V_O > -0.5V$ or $V_O < V_{CC} + 0.5V$ ±25mA
DC V <sub>CC</sub> or Ground Current, I <sub>CC or</sub> I <sub>GND</sub>

#### **Thermal Information**

Thermal Resistance (Typical, Note 3)	$\theta_{JA}$ (°C/W)
PDIP Package	90
Maximum Junction Temperature	150 <sup>o</sup> C
Maximum Storage Temperature Range65	5°C to 150°C
Maximum Lead Temperature (Soldering 10s)	300°C
(SOIC - Lead Tips Only)	

### **Operating Conditions**

Temperature Range, T <sub>A</sub>	C,
Supply Voltage Range, V <sub>CC</sub>	
HC Types2V to 6	۷
HCT Types	۷
DC Input or Output Voltage, $V_I, V_O$ 0V to $V_C$	C
Input Rise and Fall Time	
2V	x)
4.5V 500ns (Ma	x)
6V	x)

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

#### NOTE:

3.  $\theta_{\mbox{\scriptsize JA}}$  is measured with the component mounted on an evaluation PC board in free air.

## **DC Electrical Specifications**

		TES CONDIT		V <sub>CC</sub>		25°C			O 85°C	-55°C T				
PARAMETER	SYMBOL	V <sub>I</sub> (V)	I <sub>O</sub> (mA)	(V)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNITS		
High Level Input	V <sub>IH</sub>	-	-	2	1.5	-	-	1.5	-	1.5	-	V		
Voltage				4.5	3.15	-	-	3.15	-	3.15	-	V		
				6	4.2	-	-	4.2	-	4.2	-	V		
Low Level Input	V <sub>IL</sub>	-	-	2	-	-	0.5	-	0.5	-	0.5	V		
Voltage				4.5	-	-	1.35	-	1.35	-	1.35	V		
				6	-	-	1.8	-	1.8	-	1.8	V		
High Level Output	V <sub>OH</sub>	V <sub>IH</sub> or V <sub>IL</sub>	-0.02	2	1.9	-	-	1.9	-	1.9	-	V		
Voltage CMOS Loads			-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V		
OMOO Edddo			-0.02	6	5.9	-	-	5.9	-	5.9	-	V		
High Level Output			-	-	-	-	-	-	-	-	-	V		
Voltage TTL Loads			-4	4.5	3.98	-	-	3.84	-	3.7	-	V		
112 20000			-5.2	6	5.48	-	-	5.34	-	5.2	-	V		
Low Level Output	V <sub>OL</sub>	V <sub>IH</sub> or V <sub>IL</sub>	0.02	2	-	-	0.1	-	0.1	-	0.1	V		
Voltage CMOS Loads				0.02	4.5	-	-	0.1	-	0.1	-	0.1	V	
Omoo Edado							0.02	6	-	-	0.1	-	0.1	-
Low Level Output			-	-	-	-	-	-	-	-	-	V		
Voltage TTL Loads			4	4.5	-	-	0.26	-	0.33	-	0.4	V		
			5.2	6	-	-	0.26	-	0.33	-	0.4	V		
Input Leakage Current	II	V <sub>CC</sub> or GND	-	6	-	-	±0.1	-	±1	-	±1	μА		
Quiescent Device Current	lcc	V <sub>CC</sub> or GND	0	6	-	-	8	-	80	-	160	μΑ		

NOTE: For dual-supply systems theoretical worst case ( $V_I = 2.4V$ ,  $V_{CC} = 5.5V$ ) specification is 1.8mA.

## CD74HC4017

# **Prerequisite for Switching Specifications**

		TEST	V <sub>CC</sub> (V)		25°C		-40°C 1	O 85°C	-55°C TO 125°C		
PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNITS
Maximum Clock	f <sub>MAX</sub>	-	2	6	-	-	5	-	4	-	MHz
Frequency			4.5	30	-	-	35	-	20	-	MHz
			6	35	-	-	49	-	23	-	MHz
CP Pulse Width	t <sub>W</sub>	-	2	80	-	-	100	-	120	-	ns
			4.5	16	-	-	20	-	24	-	ns
			6	14	-	-	17	-	20	-	ns
MR Pulse Width	t <sub>W</sub>	-	2	80	-	-	100	-	120	-	ns
			4.5	16	-	-	20	-	24	-	ns
			6	14	-	-	17	-	20	-	ns
Set-up Time,	t <sub>SU</sub>	-	2	75	-	-	95	-	110	-	ns
CE to CP			4.5	15	-	-	19	-	22	-	ns
			6	13	-	-	16	-	19	-	ns
Hold Time,	t <sub>H</sub>	-	2	0	-	-	0	-	0	-	ns
CE to CP			4.5	0	-	-	0	-	0	-	ns
			6	0	-	-	0	-	0	-	ns
MR Removal Time	t <sub>REM</sub>	-	2	5	-	-	5	-	5	-	ns
			4.5	5	-	-	5	-	5	-	ns
			6	5	-	-	5	-	5	-	ns

## Switching Specifications Input $t_r$ , $t_f = 6ns$

		TEST	V <sub>CC</sub>		25°C			-40°C TO 85°C		-55°C TO 125°C	
PARAMETER	SYMBOL	CONDITIONS	(V)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNITS
Propagation Delay	t <sub>PLH,</sub>	C <sub>L</sub> = 50pF	2	-	-	230	-	290	-	345	ns
CP to any Dec. Out	t <sub>PHL</sub>	C <sub>L</sub> = 50pF	4.5	-	-	46	-	58	-	69	ns
		C <sub>L</sub> = 15pF	5	-	19	-	-	-	-	-	ns
		C <sub>L</sub> = 50pF	6	-	-	39	-	49	-	59	ns
CP to TC	t <sub>PLH,</sub>	C <sub>L</sub> = 50pF	2	-	-	230	-	290	-	345	ns
	<sup>t</sup> PHL	C <sub>L</sub> = 50pF	4.5	-	-	46	-	58	-	69	ns
		C <sub>L</sub> = 15pF	5	-	19	-	-	-	-	-	ns
		C <sub>L</sub> = 50pF	6	-	-	39	-	49	-	59	ns
CE to any Dec. Out	t <sub>PLH,</sub>	C <sub>L</sub> = 50pF	2	-	-	250	-	315	-	375	ns
		C <sub>L</sub> = 50pF	4.5	-	-	50	-	63	-	75	ns
		C <sub>L</sub> = 15pF	5	-	21	-	-	-	-	-	ns
		C <sub>L</sub> = 50pF	6	-	-	43	-	54	-	64	ns
CE to TC	t <sub>PLH,</sub> t <sub>PHL</sub>	C <sub>L</sub> = 50pF	2	-	-	250	-	315	-	375	ns
		C <sub>L</sub> = 50pF	4.5	-	-	50	-	63	-	75	ns
		C <sub>L</sub> = 15pF	5	-	21	-	-	-	-	-	ns
		C <sub>L</sub> = 50pF	6	-	-	43	-	54	-	64	ns

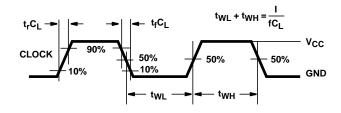
#### Switching Specifications Input $t_r$ , $t_f = 6ns$ (Continued)

		TEST	V <sub>CC</sub>	25°C			-40 <sup>o</sup> (		-55°C TO 125°C		
PARAMETER	SYMBOL	CONDITIONS	(V)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNITS
MR to any Dec. Out	t <sub>PLH</sub> ,	C <sub>L</sub> = 50pF	2	-	-	230	-	290	-	345	ns
	t <sub>PHL</sub>	C <sub>L</sub> = 50pF	4.5	-	-	46	i	58	-	69	ns
		C <sub>L</sub> = 15pF	5	-	19	-	-	-	-	-	ns
		C <sub>L</sub> = 50pF	6	-	-	39	-	49	-	59	ns
MR to TC	t <sub>PLH</sub> ,	C <sub>L</sub> = 50pF	2	-	-	230	-	290	-	345	ns
t <sub>F</sub>	t <sub>PHL</sub>	C <sub>L</sub> = 50pF	4.5	-	-	46	-	58	-	69	ns
		C <sub>L</sub> = 15pF	5	-	19	-	-	-	-	-	ns
		C <sub>L</sub> = 50pF	6	-	-	39	-	49	-	59	ns
Transition Time TC, Dec. Out	t <sub>TLH</sub> , t <sub>THL</sub>	C <sub>L</sub> = 50pF	2	-	-	75	-	95	-	110	ns
		C <sub>L</sub> = 50pF	4.5	-	-	15	-	19	-	22	ns
		C <sub>L</sub> = 50pF	6	-	-	13	-	16	-	19	ns
Input Capacitance	C <sub>IN</sub>	C <sub>L</sub> = 50pF	-	-	-	10	-	10	-	10	pF
Maximum CP Frequency	f <sub>MAX</sub>	C <sub>L</sub> = 15pF	5	-	60	-	-	-	-	-	MHz
Power Dissipation Capacitance (Notes 4, 5)	C <sub>PD</sub>	C <sub>L</sub> = 15pF	5	-	39	-	-	-	-	-	pF

#### NOTES:

- 4.  $C_{\mbox{PD}}$  is used to determine the dynamic power consumption, per package.
- 5.  $P_D = V_{CC}^2 f_i \Sigma C_L V_{CC}^2$  fo where  $f_i$  = input frequency,  $f_0$  = output frequency,  $C_L$  = output load capacitance,  $V_{CC}$  = supply voltage.

## Test Circuits and Waveforms



NOTE: Outputs should be switching from 10%  $V_{CC}$  to 90%  $V_{CC}$  in accordance with device truth table. For  $f_{MAX}$ , input duty cycle = 50%.

FIGURE 1. HC CLOCK PULSE RISE AND FALL TIMES AND PULSE WIDTH

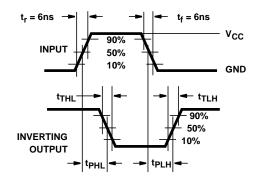


FIGURE 2. HC TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC

# Test Circuits and Waveforms (Continued)

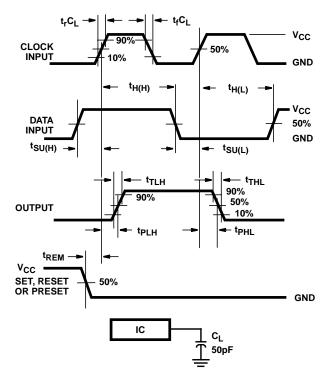
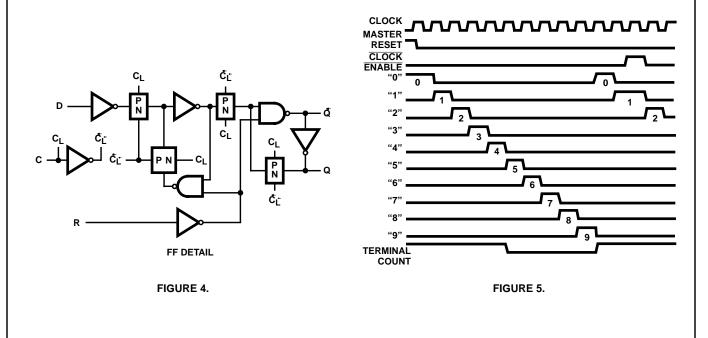


FIGURE 3. HC SETUP TIMES, HOLD TIMES, REMOVAL TIME, AND PROPAGATION DELAY TIMES FOR EDGE TRIGGERED SEQUENTIAL LOGIC CIRCUITS

# **Timing Diagrams**



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